

A method for securing a multi-dimensionally constructed chip stack, which has a plurality of part chips which are interconnected at respective contact areas and of which at least one contains functional components, includes the steps of providing respective conductor tracks in the part chips and providing feed-through contacts at the respective contact areas, which in each case interconnect conductor tracks of various part chips so that a continuous electrical signal path running through the part chips is formed. An electrical signal is transmitted from a transmitting device provided at a first end of the electrical signal path to a receiving device provided at a second end of the electrical signal path. When the electrical signal cannot be received, it is determined that the chip stack has been damaged. A device for securing a chip stack and a chip configuration are also provided.

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